

Zymet UA-3307-B Edgebond Adhesive for Automotive Board Level Reliability

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EAST HANOVER, NJ – Zymet has introduced UA-3307-B, a new edgebond adhesive to enhance board level reliability in automotive and other harsh environment applications. BGA's whose corners and edges are bonded with this adhesive have passed more than 2000 cycles of -40°C to 125°C thermal cycling without failure. Large WLP's, exceeding 8-mm in size, have passed more than 1500 cycles. The good results are attributable to the adhesive's high Tg, 149°C, and low CTE, 15 ppm/°C.

The benefits of using Zymet's edgebond adhesive, rather than introducing an underfill under the component, are significant. Board preheat and dwell time are not needed for underfill flow. There is no risk of underfill voids caused by flux residues impeding flow. And, there is no risk of underfill/flux-residue chemical incompatibility affecting underfill cure. Use of Zymet's UA-3307-B is simple, repeatable, and reliable.

For more information, visit Zymet at SMTA International 2017, at the Donald E. Stephens Convention Center in Rosemont IL, September 17-21, 2017, Booth 1032. Or, email the company at info@zymet.com. Zymet is a global supplier of adhesives and encapsulants, focused on the development and manufacture of enabling materials for the electronics industry.



Figure 1. WLP bonded with a reworkable edgebond adhesive, courtesy of Zymet, Inc.